



# DONGGUAN XINGLIN ELECTRONICS CO.,LTD

## SOD-882 High-speed Switching Diode

### BAS16L

#### DESCRIPTION

The BAS16L is a high-speed switching diode fabricated in planar technology and encapsulated in a SOD882 leadless ultra small plastic package.

#### FEATURES

- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 500 mA
- Leadless ultra small plastic package (1 mm × 0.6 mm × 0.5 mm)
- Board space 1.17 mm<sup>2</sup> (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

#### APPLICATIONS

- General purpose switching in surface mounted circuits
- Mobile communication, digital (still) cameras, PDA and PCMCIA cards.

**Marking code:** S2.

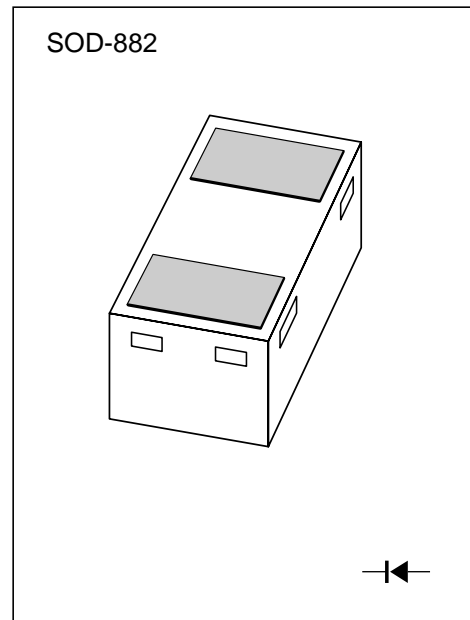
#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage		–	100	V
V <sub>R</sub>	continuous reverse voltage		–	75	V
I <sub>F</sub>	continuous forward current	see Fig.2; note 1	–	215	mA
I <sub>FRM</sub>	repetitive peak forward current		–	500	mA
I <sub>FSM</sub>	non-repetitive peak forward current	square wave; T <sub>j</sub> = 25 °C prior to surge; see Fig.4 t = 1 μs t = 1 ms t = 1 s	– – –	4 1 0.5	A A A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C; note 1	–	250	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C

#### Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with 60 μm copper strip line.





**ELECTRICAL CHARACTERISTICS**

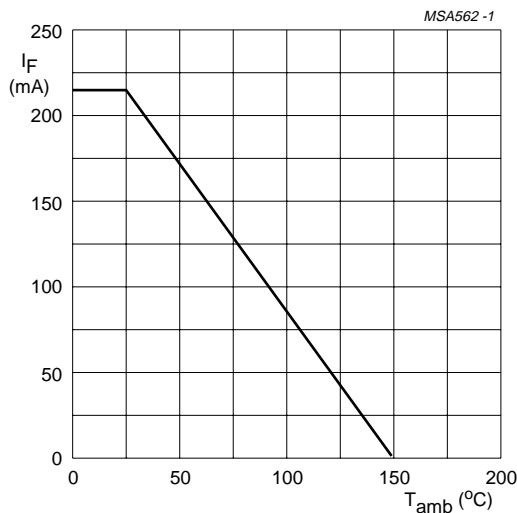
T<sub>amb</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.3 I <sub>F</sub> = 1 mA I <sub>F</sub> = 10 mA I <sub>F</sub> = 50 mA I <sub>F</sub> = 150 mA	715 855 1 1.25	mV mV V V
I <sub>R</sub>	reverse current	see Fig.5 V <sub>R</sub> = 25 V V <sub>R</sub> = 75 V V <sub>R</sub> = 25 V; T <sub>j</sub> = 150 °C V <sub>R</sub> = 75 V; T <sub>j</sub> = 150 °C	30 1 30 50	nA μA μA μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0 V; f = 1 MHz; see Fig.6	1.5	pF
t <sub>rr</sub>	reverse recovery time	when switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 10 mA; R <sub>L</sub> = 100 Ω; measured at I <sub>R</sub> = 1 mA;	4	ns
V <sub>fr</sub>	forward recovery voltage	when switched from I <sub>F</sub> = 10 mA; t <sub>r</sub> = 20 ns	1.75	V

**THERMAL CHARACTERISTICS**

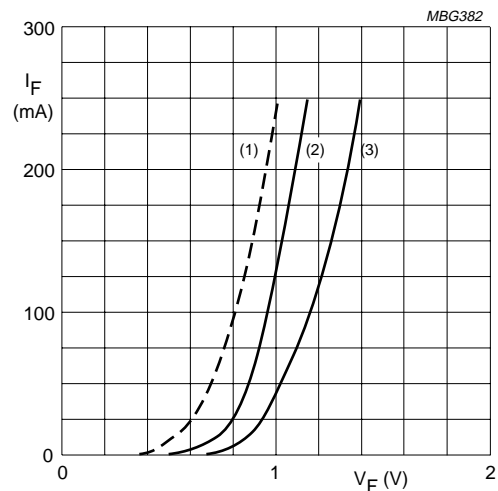
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

**GRAPHICAL DATA**



Device mounted on an FR4 printed-circuit board.

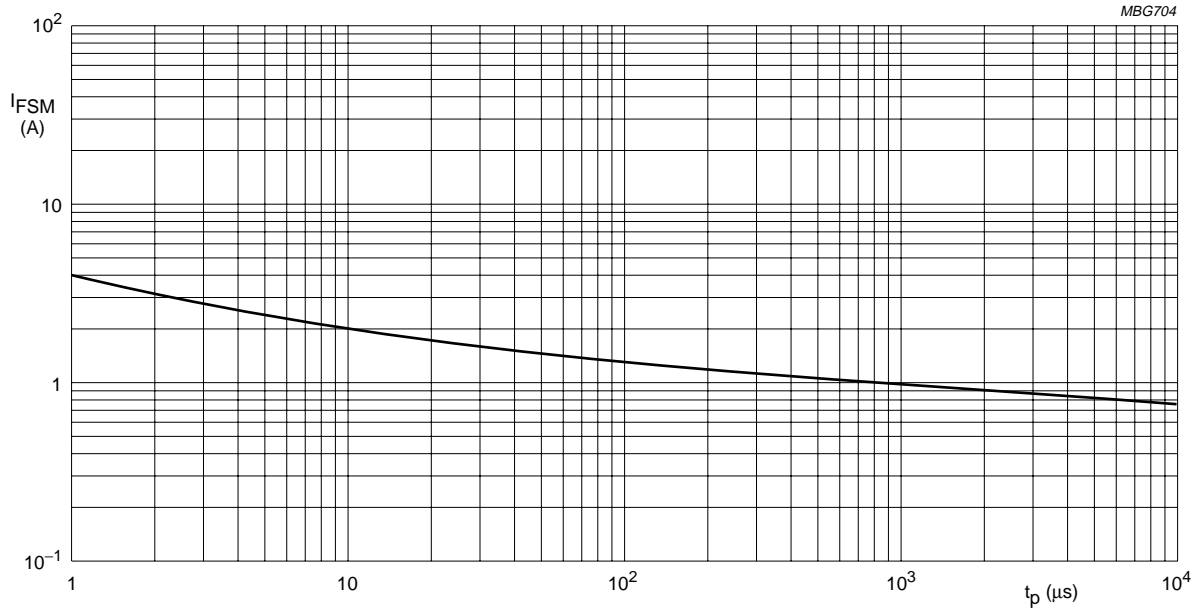
Fig.2 Maximum permissible continuous forward current as a function of ambient



- (1) T<sub>j</sub> = 150 °C; typical values.
- (2) T<sub>j</sub> = 25 °C; typical values.
- (3) T<sub>j</sub> = 25 °C; maximum value.

Fig.3 Forward current as a function of forward





Based on square wave currents.  
 $T_j = 25\text{ }^\circ\text{C}$  prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

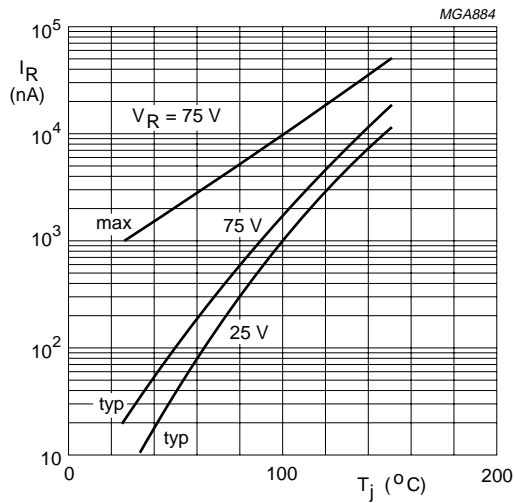
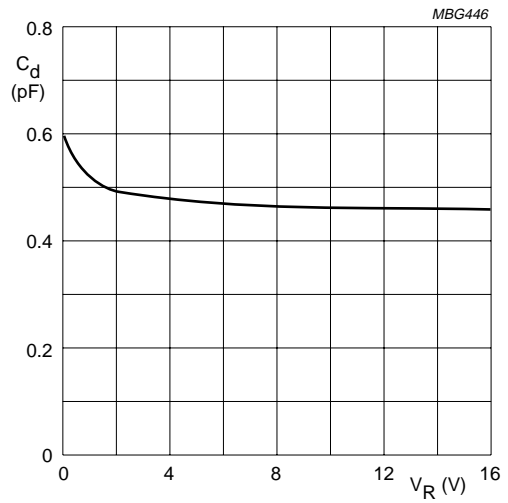


Fig.5 Reverse current as a function of junction temperature.



$f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$ .

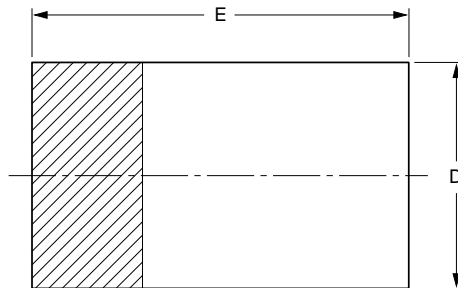
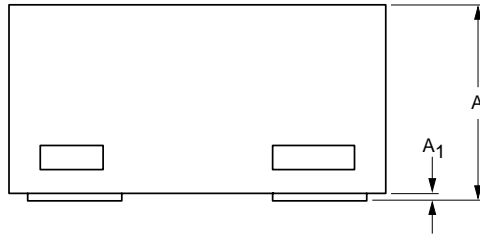
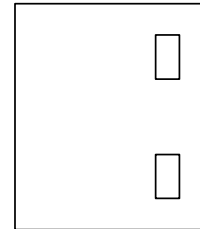
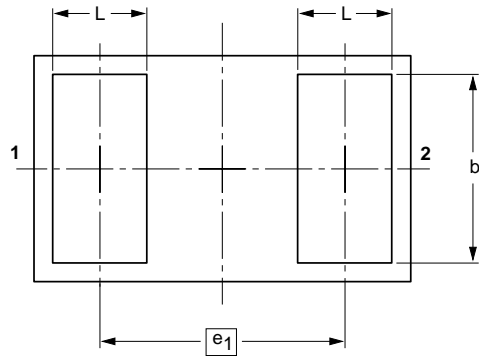
Fig.6 Diode capacitance as a function of reverse voltage; typical values.



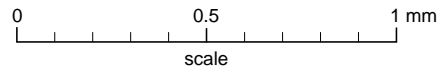
PACKAGE OUTLINE

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882



(2)



DIMENSIONS (mm are the original dimensions)

UNIT	A <sup>(1)</sup>	A <sub>1</sub> max.	b	D	E	e <sub>1</sub>	L
mm	0.50 0.46	0.03	0.55 0.47	0.62 0.55	1.02 0.95	0.65	0.30 0.22

Notes

- Including plating thickness
- The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD882						03-04-16 03-04-17

